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(54) **MOLDING METHOD AND MOLDING DEVICE UTILIZING ULTRASONIC VIBRATION AND OPTICAL LENS**

(57) A molding method is provided which can further improve transferability and further reduce strain and which is suitable for molding of a product with high accuracy and high quality.

The molding method in which a resin material is filled into a cavity formed in a mold and pressurized to mold a product in a predetermined shape, and the method comprises: preparing the mold having a product cavity to mold the product made of a resin, a dummy cavity to mold a dummy product, and a runner by which the product cavity and the dummy cavity are connected; filling the resin material into the product cavity and supplying the resin material to at least part of the dummy cavity; and applying ultrasonic vibration to the resin material in the dummy cavity at predetermined timing.

FIG. 1(a)

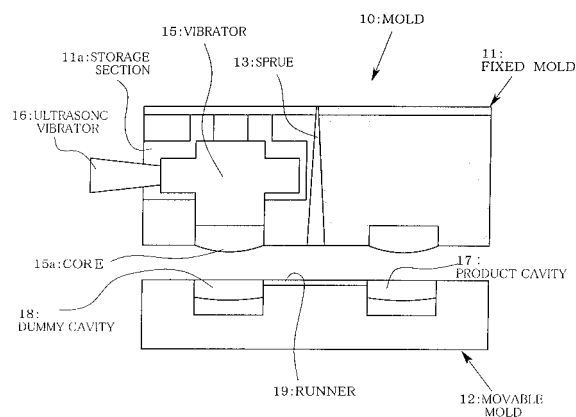


FIG. 1(b)

